

## Claims

1. An epoxy resin composition for a printed wiring board, comprising an epoxy resin, a phenol novolac resin, a curing accelerator and a silica filler, characterized in that, as the silica filler, is used a silica filler which has a shape having at least two planes, and has an average particle diameter between  $0.3\ \mu\text{m}$  and  $10\ \mu\text{m}$  and a relative surface area between  $8\ \text{m}^2/\text{g}$  and  $30\ \text{m}^2/\text{g}$ .
2. An epoxy resin composition for a printed wiring board as described in claim 1, characterized in that, as said silica filler defined in claim 1, is used a silica filler having at least two planes in the shape, an average particle diameter between  $0.3\ \mu\text{m}$  and  $10\ \mu\text{m}$  and a relative surface area between  $10\ \text{m}^2/\text{g}$  and  $20\ \text{m}^2/\text{g}$ .
3. An epoxy resin composition for a printed wiring board as described in claims 1 or 2, characterized in that said silica filler defined in claim 1 or 2 is added in an amount of from 3% to 80% by weight per the solid content of the resin.
4. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 3, characterized in that, as said silica filler defined in claim 1, is used a silica filler having an electric conductivity of  $15\ \mu\text{S}$  or less.
5. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 4, characterized in that, as said silica filler defined in claim 1 or 2, is used a silica filler which has been vitrified through melting at a temperature of  $1800^\circ\text{C}$  or higher.
6. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 5, characterized in that, as said epoxy resin, is used an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin obtained by reacting a dihydric phenol with a bisphenol A type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.
7. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 5, characterized in that, as said epoxy resin, is used an epoxy resin having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing an epoxy resin possessing a dicyclopentadienyl structure in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.
8. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 5, characterized in that, as said epoxy resin, is used an epoxy resin

having a bromine content of between 5% and 20% by weight per the solid content of the resin without silica filler and containing of a novolac type epoxy resin in an amount of between 40% and 100% by weight based on the whole amount of the epoxy resin solid content.

9. An epoxy resin composition for a printed wiring board as described in any one of claims 1 to 5, characterized in that, as said epoxy resin composition, is used a bromine-free epoxy resin composition.
10. A prepreg for a printed wiring board, characterized in that the prepreg is obtained by impregnating a reinforcing material with an epoxy resin composition for a printed wiring board as described in any one of claims 1 to 9 and drying said composition to B-stage.
11. A laminated board for a printed wiring board, characterized in that the board is obtained by gluing a prepreg as described in claim 10 to a surface of a metal foil and hot pressing them.
12. A printed wiring board, characterized in that the board is obtained by using a laminated board for a printed wiring board as described in claim 11.